

IN THE CLAIMS

1 (Original). An integrated circuit socket comprising:
a socket housing;
a hinged cover secured to said housing; and
an infrared transmissive cap removably secured to said cover.

2 (Previously Presented). The socket of claim 1 wherein said cap includes a plurality of openings formed through the cap to allow the passage of heated air.

3 (Original). The socket of claim 1 including spring catches on opposed ends of said cap to removeably secure said cap to said cover.

4 (Original). The socket of claim 1 wherein said cap transmits at least 80 percent of incident infrared radiation.

5 (Original). The socket of claim 4 wherein said cap transmits at least 95 percent of incident infrared radiation.

6 (Original). The socket of claim 1 wherein said cap is formed of plastic.

7 (Original). The socket of claim 6 wherein said cap is formed of translucent red plastic.

8 (Original). The socket of claim 1 wherein said cap includes standoffs to space said cap from said cover.

9 (Original). The socket of claim 1 wherein said cap has a curved lower surface.

10 (Original). The socket of claim 1 wherein said cap includes at least two apertures and downwardly extending prongs extending away from said apertures to reflect incident radiation passing through said apertures.

11 (Original). A cap for an integrated circuit socket comprising:
a body having apertures therethrough, said body formed of a material that is infrared transmissive; and
tabs coupled to said body to removeably secure said body to an integrated circuit socket.

12 (Original). The cap of claim 11 wherein said tabs include spring catches on opposed ends of said cap to removeably secure said cap to said socket.

13 (Previously Presented). The cap of claim 11 wherein said cap transmits at least 80 percent of incident infrared radiation.

14 (Original). The cap of claim 13 wherein said cap transmits at least 95 percent of incident infrared radiation.

15 (Original). The cap of claim 11 wherein said cap is formed of plastic.

16 (Original). The cap of claim 15 wherein said cap is formed of translucent red plastic.

17 (Original). The cap of claim 11 wherein said cap includes standoffs to space said cap from said socket.

18 (Original). The cap of claim 11 wherein said cap has a curved side.

19 (Original). The cap of claim 11 wherein said apertures include downwardly extending prongs to reflect infrared radiation passing through said apertures.

20 (Original). The cap of claim 11 wherein said cap includes guides to guide said cap into alignment with said socket.

21 (Original). A method comprising:

securing an infrared transmissive cap to an integrated circuit socket;
exposing said cap and said socket to infrared energy; and
surface mounting said socket to a printed circuit board.

22 (Original). The method of claim 21 including exposing said cap and said socket to a surface mount reflow oven producing both infrared and convective heating.

23 (Original). The method of claim 21 including allowing heated air to circulate through said cap via apertures through said cap.

24 (Original). The method of claim 21 including providing an apertured, red plastic, infrared transmissive cap on said socket.

25 (Original). The method of claim 21 including enabling at least 80 percent of the infrared incident energy to pass through said cap to said socket.